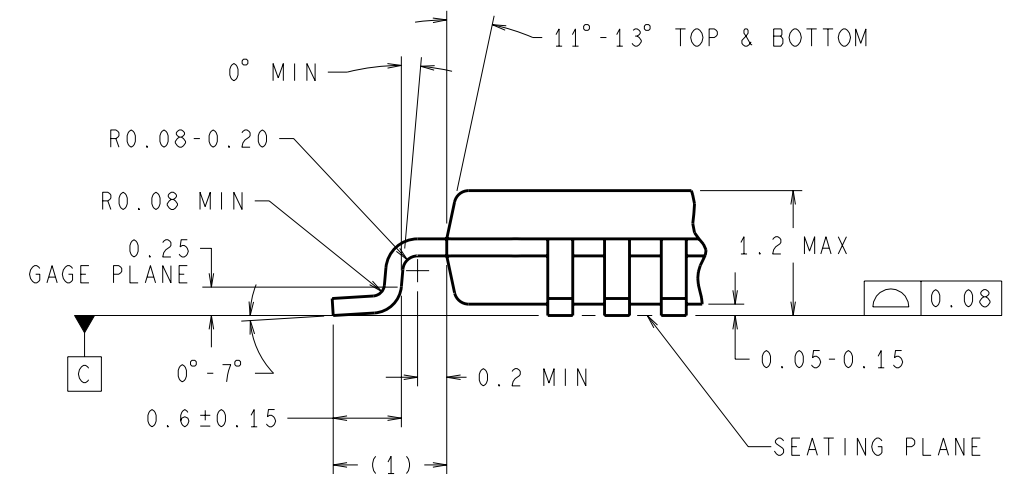
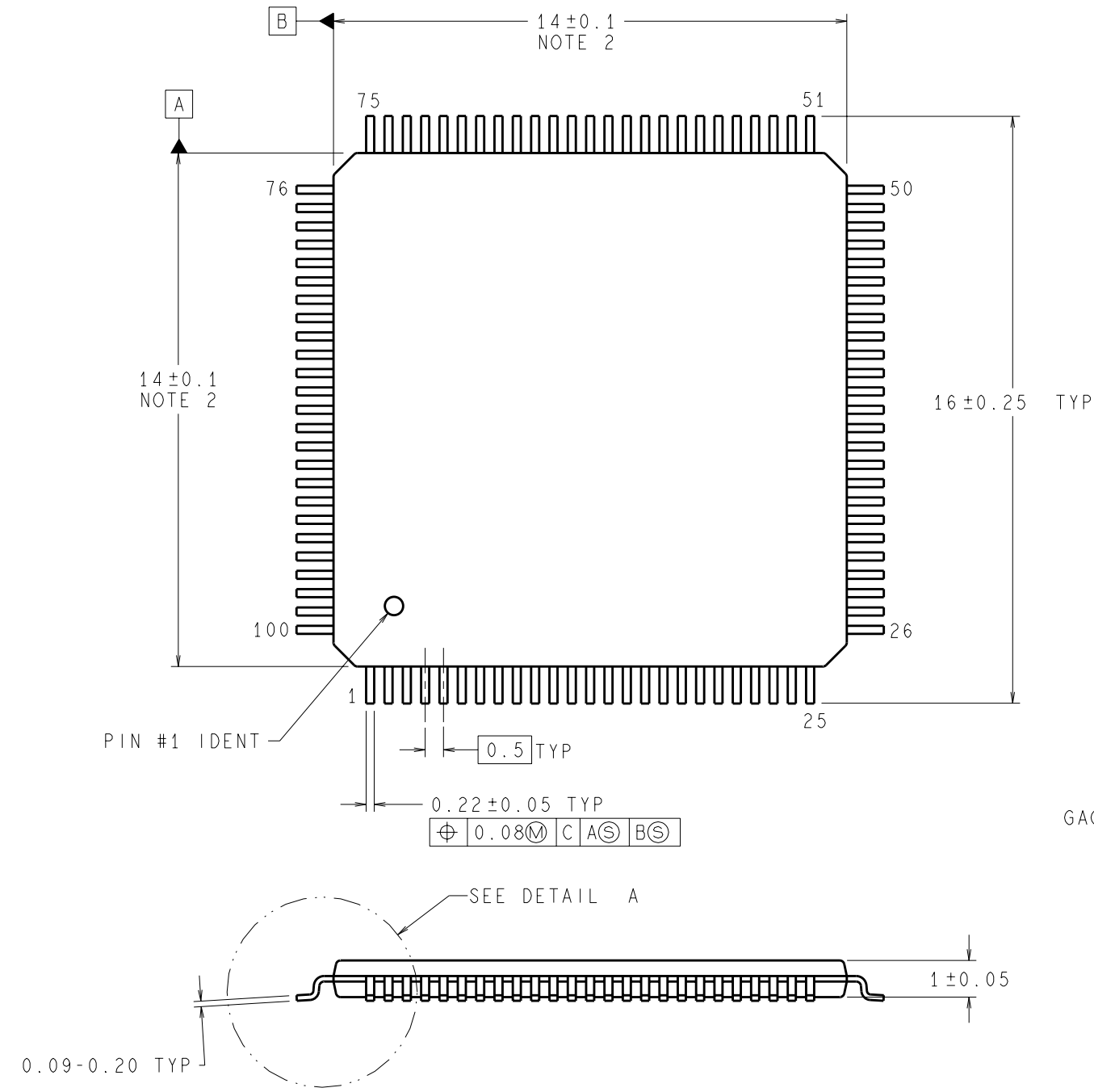


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL.	10712	11/22/1999	DEG/HJK
B	TITLE: TOFP WAS POFP; UPDATE NOTE 3; ADD GEOMETRIC TOLERANCE	12317	12/02/1999	ACS/MS/RW



DIMENSIONS ARE IN MILLIMETERS

- NOTES: UNLESS OTHERWISE SPECIFIED
- STANDARD LEAD FINISH:  
7.62 MICROMETERS MINIMUM SOLDER PLATING (85/15)  
THICKNESS ON COPPER.
  - DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.  
MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
  - REFERENCE JEDEC REGISTRATION MS-026, VARIATION AED,  
DATED FEB 1999.

APPROVALS		DATE		 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAWN D.E. Grady		11/22/1994			
DFTG. CHK. THANH LEQUANG		12/07/1999			
ENGR. CHK. RANDALL WALBERG		12/07/1999		<b>TOFP, JEDEC METRIC, 14 X 14 X 1.0mm, 100 LEAD</b>	
 INCH [MM]		SCALE N/A	SIZE C		
FORMERLY:				SHEET 1 of 1	